

Title (en)  
THERMOSETTING RESIN COMPOSITION, PREPREG MADE THEREFROM, LAMINATE CLAD WITH METAL FOIL, AND HIGH-FREQUENCY CIRCUIT BOARD

Title (de)  
WÄRMEHÄRTENDE HARZZUSAMMENSETZUNG, DARAUS HERGESTELLTES PREPREG, LAMINAT MIT METALLFOLIENKASCHIERUNG UND HOCHFREQUENZLEITERPLATTE

Title (fr)  
COMPOSITION DE RÉSINE THERMODURCISSABLE, PRÉIMPRÉGNÉ FABRIQUÉ À PARTIR DE CELLE-CI, STRATIFIÉ REVÊTU DE FEUILLE MÉTALLIQUE, ET CARTE DE CIRCUIT IMPRIMÉ HAUTE FRÉQUENCE

Publication  
**EP 3660026 A1 20200603 (EN)**

Application  
**EP 17918939 A 20171102**

Priority  
• CN 201710618306 A 20170726  
• CN 2017109051 W 20171102

Abstract (en)  
Disclosed are a thermosetting resin composition, a prepreg made therefrom, a laminate clad with a metal foil, and a high-frequency circuit board, wherein the thermosetting resin composition contains thermosetting ingredients. The thermosetting ingredients include a phosphorus-containing monomer or a phosphorus-containing resin and another thermosetting resin containing an unsaturated group, and the phosphorus-containing monomer or the phosphorus-containing resin has a structure as shown in formula I. By using the phosphorus-containing monomer or the phosphorus-containing resin as a cross-linking agent of the other thermosetting resin containing an unsaturated group and by means of a cross-linking reaction of a large number of unsaturated double bonds in the resin, the high-frequency dielectric properties and high-temperature-resistance required by a circuit substrate are provided.

IPC 8 full level  
**C07F 9/6574** (2006.01)

CPC (source: CN EP KR US)  
**B32B 15/08** (2013.01 - CN EP KR US); **B32B 15/14** (2013.01 - KR); **C07F 9/657172** (2013.01 - CN KR); **C07F 9/6574** (2013.01 - EP KR); **C08F 2/44** (2013.01 - CN EP KR); **C08F 8/40** (2013.01 - KR); **C08F 212/36** (2013.01 - KR); **C08F 222/40** (2013.01 - CN EP KR US); **C08F 230/02** (2013.01 - EP KR); **C08F 279/02** (2013.01 - KR US); **C08F 283/06** (2013.01 - KR); **C08F 287/00** (2013.01 - CN KR); **C08F 290/14** (2013.01 - EP KR); **C08F 297/02** (2013.01 - EP KR); **C08F 299/022** (2013.01 - CN EP KR US); **C08G 8/30** (2013.01 - KR); **C08G 8/36** (2013.01 - KR); **C08J 5/04** (2013.01 - KR); **C08J 5/24** (2013.01 - KR); **C08J 5/244** (2021.05 - CN EP US); **C08L 61/14** (2013.01 - KR); **C08L 71/126** (2013.01 - KR); **H05K 1/024** (2013.01 - KR US); **H05K 1/03** (2013.01 - EP); **H05K 1/0326** (2013.01 - CN KR); **H05K 1/0366** (2013.01 - KR); **H05K 1/0373** (2013.01 - KR US); **B32B 2260/021** (2013.01 - KR); **B32B 2260/046** (2013.01 - KR); **B32B 2262/00** (2013.01 - KR); **B32B 2457/00** (2013.01 - CN); **B32B 2457/08** (2013.01 - KR US); **C08F 8/40** (2013.01 - EP); **C08J 2351/00** (2013.01 - CN KR US); **C08J 2355/00** (2013.01 - CN KR); **C08K 2201/003** (2013.01 - CN KR); **H05K 2201/012** (2013.01 - KR US)

C-Set (source: CN EP US)  
CN  
**C08F 287/00 + C08F 230/02**  
EP  
1. **C08F 297/02 + C08F 230/02**  
2. **C08F 297/02 + C08F 230/02 + C08F 222/40**  
3. **C08F 290/14 + C08F 230/02 + C08F 222/40**  
US  
1. **C08F 297/02 + C08F 230/02 + C08F 222/40**  
2. **C08F 290/14 + C08F 230/02 + C08F 222/40**

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
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